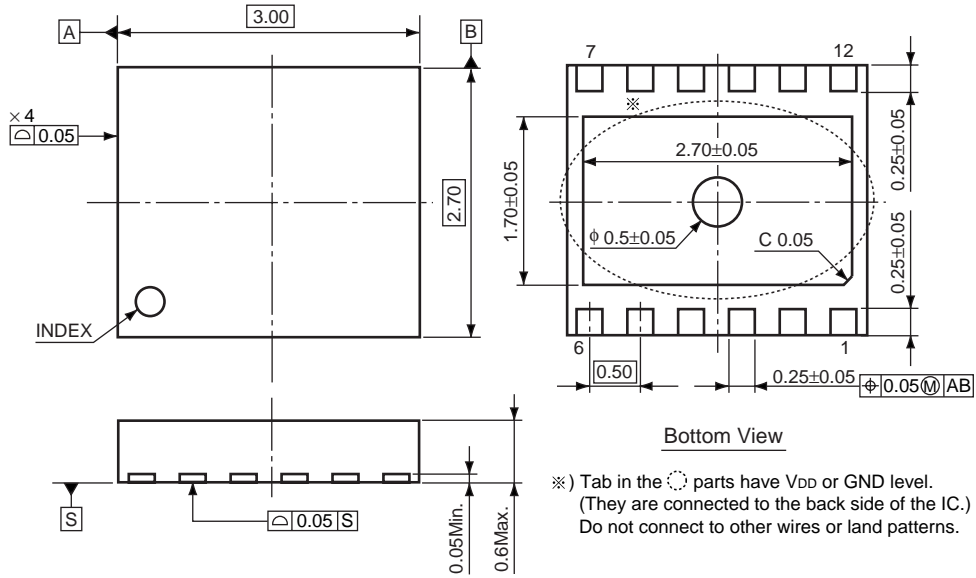


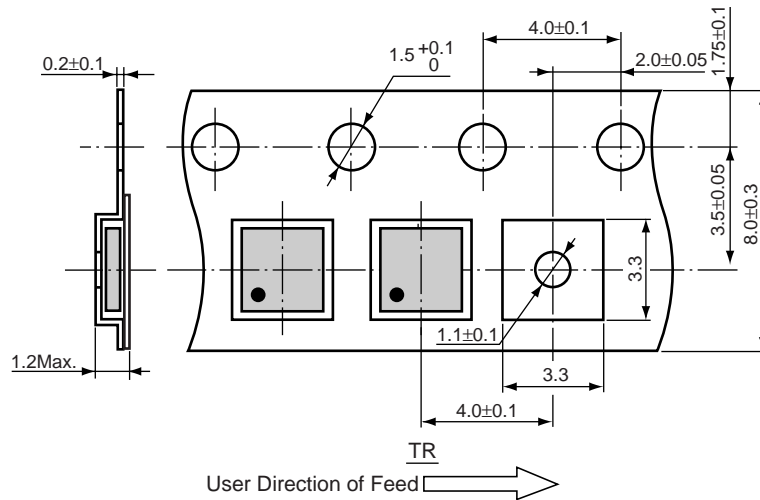
• DFN(PLP)2730-12

Unit: mm

PACKAGE DIMENSIONS

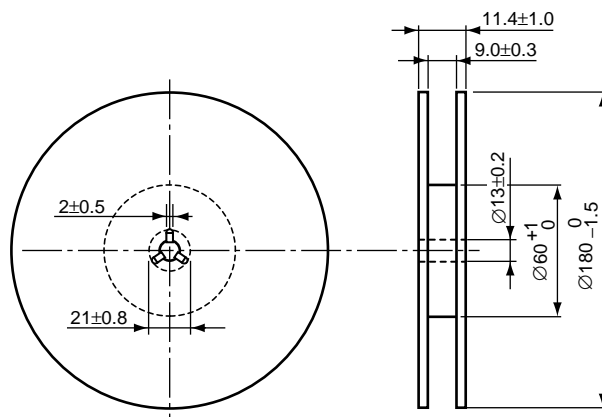


TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-08Bc)

(1reel=5000pcs)



POWER DISSIPATION (DFN(PLP)2730-12)

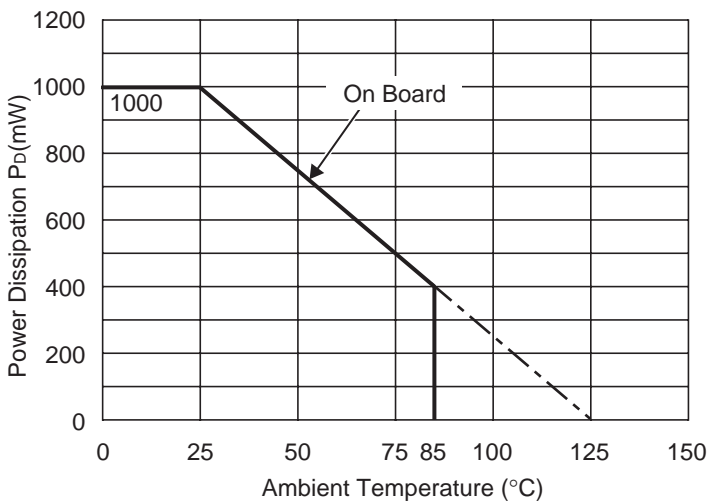
This specification is at mounted on board. Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

Measurement Conditions

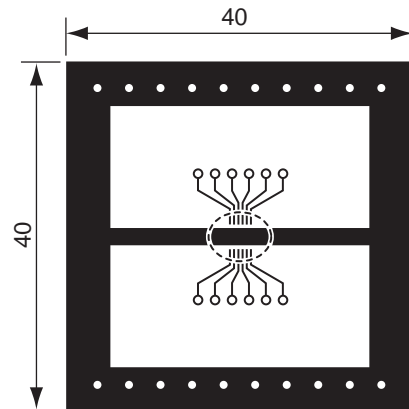
	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)
Board Dimensions	40mm × 40mm × 1.6mm
Copper Ratio	Top side : Approx. 50% , Back side : Approx. 50%
Through-hole	φ0.54mm × 32pcs

Measurement Result (T_{opt}=25°C, T_{jmax}=125°C)

	Standard Land Pattern
Power Dissipation	1000mW
Thermal Resistance	$\theta_{ja}=(125-25^{\circ}\text{C})/1.0\text{W}=100^{\circ}\text{C/W}$
Thermal Resistance	$\theta_{jc}=18^{\circ}\text{C/W}$



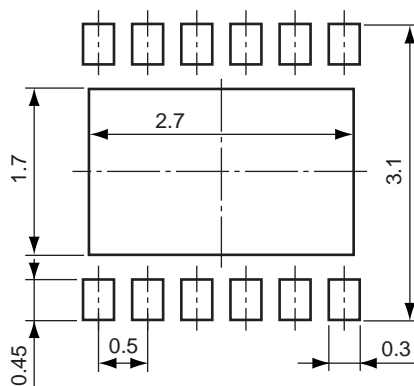
Power Dissipation



Measurement Board Pattern

○ IC Mount Area (Unit : mm)

RECOMMENDED LAND PATTERN



(Unit: mm)